

REMARKS

Claim 61-100 are pending.

I. RESTRICTION REQUIREMENT

The Examiner has set forth the following restriction requirement:

<u>Species</u>	<u>Description</u>
1	A semiconductor device package comprising: an insulative housing that contacts a chip.
2	A semiconductor device package comprising: an insulative housing that covers the lower surface and contacts the chip, and wherein an electrically conductive path between and in contact with the lead and the pad is devoid of a wire bond.
3	A semiconductor device package comprising: an insulative housing that contacts and covers the lower surface, wherein the peripheral portion is integral with the peripheral and inner side surfaces and non-integral with the central portion, the peripheral portion protrudes downwardly from the central portion, and the top and bottom surfaces, peripheral and inner side surfaces and peripheral and central portions are exposed, and wherein an electrically conductive path between and in contact with the lead and the pad is devoid of a wire bond.
4	A semiconductor device package comprising: an insulative housing that contacts and covers the lower surface, wherein the peripheral portion is integral with the peripheral and inner side surfaces and non-integral with the central portion, the peripheral portion protrudes downwardly from the central portion, and the top and bottom surfaces, peripheral and inner side surfaces and peripheral and central portions are exposed, and wherein an electrically conductive path between and in contact with the lead and the pad is devoid of a wire bond, and the lead and the electrically conductive path are no closer to the top surface than the upper surface is to the top surface.
5	A semiconductor device package comprising: an insulative housing that contacts and covers the lower and outer side surfaces, wherein the peripheral portion is integral with the peripheral and inner side surfaces and non-integral with the central portion, the peripheral portion protrudes downwardly from the central portion, and the top and bottom surfaces, peripheral and inner side surfaces and peripheral and central portions are

exposed, and wherein the lead includes a recessed portion that contacts and extends into the insulative housing and is spaced from the top and bottom surfaces and does not overlap the chip and a non-recessed portion that contacts and extends outside the insulative housing and is adjacent to the recessed portion and the bottom surface, and an electrically conductive path between and in contact with the lead and the pad is devoid of a wire bond.

- 6 A semiconductor device package comprising: an insulative housing that contacts and covers the lower and outer side surfaces, wherein the peripheral portion is integral with the peripheral and inner side surfaces and non-integral with the central portion, the peripheral portion protrudes downwardly from the central portion, and the top and bottom surfaces, peripheral and inner side surfaces and peripheral and central portions are exposed, and wherein the lead includes a recessed portion that extends into the insulative housing and is spaced from the top and bottom surfaces and a non-recessed portion that extends outside the insulative housing and is adjacent to the recessed portion and contacts the insulative housing, the recessed and non-recessed portions each include four outer surfaces, three of the outer surfaces of the recessed and non-recessed portions that do not face in the same direction as the bottom surface are coplanar with one another where the recessed and non-recessed portions are adjacent to one another, one of the outer surfaces of the recessed and non-recessed portions that face in the same direction as the bottom surface are not coplanar with one another where the recessed and non-recessed portions are adjacent to one another, an electrically conductive path between and in contact with the lead and the pad is devoid of a wire bond, and the lead and the electrically conductive path are no closer to the top surface than the upper surface is to the top surface.

The Examiner requires Applicant to elect a single species for prosecution on the merits and a listing of all claims readable thereon, including any claims subsequently added.

Applicant provisionally elects claims 61-120 for prosecution on the merits. Applicant also traverses the restriction requirement and requests that it be withdrawn.

The restriction is flawed for several reasons.

None of the claims read on any of the species. For instance, claims 61, 71, 81, 91, 101 and 111 recite “an insulative housing with a top surface, a bottom surface, a peripheral side surface between the top and bottom surfaces, and an inner side surface opposite the peripheral side surface” and “the chip includes an upper surface, a lower surface and an outer side surface between the upper and lower surfaces, the upper surface includes a conductive pad, faces towards the central portion and faces away from the top surface” and “a lead that protrudes laterally from and extends through the peripheral side surface and is electrically connected to the pad.” None of the species includes these features.

There must be a serious burden on the examiner if the restriction is required (M.P.E.P. § 803). Where the related inventions as claimed are shown to be distinct, the Examiner, in order to establish reasons for insisting upon restriction, must show by appropriate explanation one of the following: (A) separate classification thereof; (B) a separate status in the art when they are classifiable together; or (C) a different field of search (M.P.E.P. § 808.02).

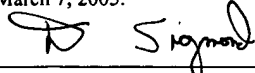
The Examiner has not even attempted to explain why the various species would involve separate classification, separate status in the art, or a different field of search (M.P.E.P. § 808.02). Applicant believes this ignores the mandatory elements set forth in the M.P.E.P. and therefore is improper.

Therefore, Applicant requests that the restriction requirement be withdrawn. First, none of the claims read on any of the species, rendering the restriction requirement moot. Second, the Examiner has not demonstrated that examining the various species constitutes a serious burden, thereby rendering the restriction requirement improper.

II. CONCLUSION

In view of the remarks set forth herein, the application is believed to be in condition for allowance. Should any issues remain, the Examiner is encouraged to telephone the undersigned attorney.

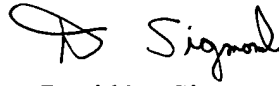
I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on March 7, 2005.



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3/7/05
Date of Signature

Respectfully submitted,



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